

Connector for Connection with PC Cards Supporting CardBus

SCAK/SCAJ Series



Highly reliable mounting achieved by unique terminal arrangement.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Eject knob can be applied to the left or right side.
- Pin header (SCAJ) is provided with an adsorption area allowing automatic mounting.

Applications

- For set top boxes, various PCs and AV equipment

Typical Specifications

Items		Specifications
Structure	Applicable media	PC cards which confirm to PC card standard
	Mounting method	Surface mounting type
	Contact pitch	1.27mm
	Number of contacts	68 pins
Performance	Operating temperature range	-20°C to +60°C
	Voltage proof	250V AC 1minute
	Insulation resistance(Initial)	1,000MΩ min.
	Contact resistance(Initial)	40mΩ max.
	Insertion and removal cycle	Office environment : 10,000cycles Outside office environment : 5,000cycles

Product Line

2 step ejector

Ejection mechanism:2step

Mounting system	Stand-off (mm)	Cover	Shutter	Position of knob	Product No.		Minimum packing unit (pcs.)
					Standard	Reverse	
Standard mount Reverse mount	0	With	Without	Left	SCAK5B7100	SCAK5B7200	180
				Right	SCAK5B7200	SCAK5B7100	
		Without		Left	SCAK5B7400	SCAK5B7500	
				Right	SCAK5B7500	SCAK5B7400	

Pin header

Mounting system	Stand-off (mm)	Product No.	Minimum packing unit (pcs.)
Standard mount	0	SCAJ1A1600	300
Reverse mount	0	SCAJ1B1500	

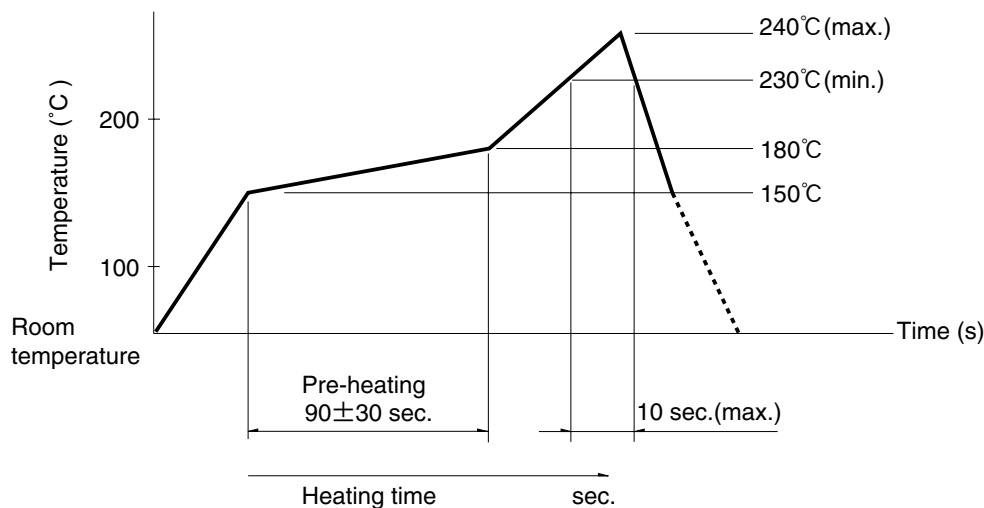
Notes

1. ※Please place purchase orders in minimum order units.
2. Please contact us for export packing details.
3. The pin headers and the ejectors are supplied as separate parts. When using them, solder a pin header to a printed circuit board, assemble an ejector to the pin header and screw it.

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile.



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.

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